6th ISEEIE 2026

2026 6th International Symposium on Electrical, Electronics and Information Engineering

2026年第六届电气、电子与信息工程国际会议

2026年10月16-18日 | 中国 · 沈阳

Welcome to ISEEIE 2026

Welcome to the 2026 6th International Symposium on Electrical, Electronics and Information Engineering (ISEEIE 2026), which will be held in Shenyang, China from October 16-18, 2026.

This symposium provides a premier platform for fostering collaboration and driving innovation among Electrical, Electronics, and Information Engineers, as well as Artificial Intelligence and Data Science professionals. With a vision to bring together experts and enthusiasts from diverse backgrounds, this symposium aims to transcend disciplinary boundaries and pave the way for ground-breaking advancements in the interconnected fields of electrical engineering, electronics, and information technology.

We extend a warm invitation to potential conference paper authors, academics, professionals, and policymakers who share our enthusiasm for pushing the boundaries of knowledge and innovation in electrical engineering, electronics, and information technology. We look forward to welcoming you to ISEEIE 2026.

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Important Dates

- Abstract Deadline: May 31, 2026
- Full Paper Deadline: June 15, 2026
- Author Notification: July 15, 2026
- Registration Deadline: August 15, 2026
- Final Paper Deadline: September 16, 2026
- Main Conference: October 16-18, 2026

Submission

ISEEIE 2026 invites submissions of original and unpublished research papers. Authors are welcome to submit their manuscripts through the Online Submission System.

Link: https://cmt3.research.microsoft.com/ISEEIE2026

Publication

Registered and presented full papers will be included in the ISEEIE 2026 digital conference proceedings (ISBN: 979-8-3195-2350-1), which will be published by IEEE and submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements, and also submitted to major citation databases (including, but not limited to Ei Compendex and Scopus) for review and indexing.

IEEE　Compendex on Engineering Village　Scopus

Event Partners

Co-sponsored By: IEEE　IEEE PES Power & Energy Society

Organized By: 沈阳理工大学 SHENYANG LIGONG UNIVERSITY　浙江大学 海南研究院 HAINAN INSTITUTE OF ZHEJIANG UNIVERSITY

Call For Papers

The topics of interest include, but are not limited to:

Electrical and Electronics Engineering

- Automation and Control Engineering
- Circuits and Systems
- Computer Network and Security
- Electrical Machines and Drive Systems
- High-Performance Motor System
- Microwave Technologies
- Power Electronics and Drive Systems
- Power System Reliability and Security
- Remote Sensing, Radar and Sensing
- Semiconductor Technology

Information Engineering

- Signal and Image Processing
- Bioinformatic
- Computer and Information Science
- Computer Graphics and Image Processing
- Geographical Information Systems (GIS)
- Image Processing and Acquisition
- Knowledge Discovery and Data Mining
- Neural Networks and Genetic Algorithms
- Pattern Recognition and Machine Learning
- Transmission of Numerical Images

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